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## Table of Contents

### INTRODUCTORY SECTION

Welcome Message  
Steering Committee  
Paper Awards  
Technical Program Committee

### PLENARY EVENTS

#### Keynote

*Testing Positive...For Complexity!*  
Aart de Geus

#### Keynote

*Automated Software Testing for the 21st Century*  
Patrice Godefroid

#### Panel

*Wisdom from the Giants*

Moderator: K. Fuchs, Organizer: S. Blanton

Panelists: J. Abraham, V. Agrawal, B. Bottoms, M. Bruer, W. Maly, S. Reddy,  
T.W. Williams

### SESSION 1 WHAT NEW DEFECTS WILL NEW TECHNOLOGIES BRING?

Session Chair: K. Khare

- 1.1 *INVITED PAPER: Process Defect Trends and Strategic Test Gaps* 1  
P. Ryan, I. Aziz, W. Howell, T. Janczak, D. Lu
- 1.2 *On the Testing of Hazard-activated Open Defects* 9  
A. Singh, C. Han
- 1.3 *Protecting Against Emerging Vmin Failures in Advanced Technology Nodes* 15  
J. Lee, A. Haggag, W. Eklow

### SESSION 2 MODELING AND MEASURING COMPLEX ANALOG BEHAVIORS

Session Chair: S. Sen

- 2.1 *Low-Cost Back-End Signal-Processing-driven Bandwidth-interleaved Signal Acquisition Using Free Running Undersampling Clocks and Mixing Signals* 22  
N. Tzou, D. Bhatta, A. Chatterjee
- 2.2 *INVITED PAPER: Analog Fault Models: Back to the Future?* 32  
M. Soma
- 2.3 *Practical Random Sampling of Potential Defects for Analog Fault Simulation* 33  
S. Sunter, K. Jurga, P. Dingenen, R. Vanhooren

## Table of Contents

### SESSION 3 SECURITY: FROM CHIPS TO THE INTERNET OF THINGS

Session Chair: C. McCants

- 3.1 *INVITED PAPER: Security Solutions in the First-Generation Zynq All- Programmable SoC* 43  
S. Trimberger
- 3.2 *INVITED PAPER: Delivering Security by Design in the Internet of Things* 44  
B. Curtis
- 3.3 *INVITED PAPER: Energy-Secure Computer Architectures* 45  
P. Bose

### SESSION 4 ROBUST ENERGY SYSTEMS

Session Chair: D. Kirschen

- 4.1 *INVITED PAPER: Dynamic Microgrids – A Potential Solution for Enhanced Resiliency in Distribution Systems* 46  
M. Vadari
- 4.2 *INVITED PAPER: Microgrids as a Resiliency Resource* 47  
K. Schneider
- 4.3 *INVITED PAPER: Recruiting Distributed Resources for Grid Resilience: The Need for Transparency* 48  
A. von Meier

### SESSION 5 DISCUSSION SESSION: HAS ADAPTIVE TEST LIVED UP TO ITS EXPECTATIONS?

Moderator: D. Glotter, Organizer: J. Roeher

- 5.1 *INVITED PAPER: Concerns over Predictability of Supply and Quality* 49  
C. Bowen
- 5.2 *INVITED PAPER: The Desire-Friction Ratio of Adaptive Test* 50  
S. Ajouri
- 5.3 *INVITED PAPER: Collaboration and Teamwork Obstacles* 51  
W. Smith
- 5.4 *INVITED PAPER: ATE and Test Equipment Vendors; Hardware Not Software* 52  
M. Roos

### SESSION 6 MORE TEST COMPRESSION: CADENCE, MENTOR, SYNOPSIS

Session Chair: X. Li

- 6.1 *Efficient Testing of Hierarchical Core-based SOCs* 53  
B. Keller, K. Chakravadhanula, B. Foutz, V. Chickermane, A. Garg, R. Schoonover, J. Sage, D. Pearl, T. Snethen
- 6.2 *Isometric Test Compression with Low Toggling Activity* 63  
A. Kumar, M. Kassab, E. Moghaddam, N. Mukherjee, J. Rajski, S.M. Reddy, J. Tyszer, C. Wang
- 6.3 *Achieving Extreme Scan Compression for SoC Designs* 70  
P. Wohl, J. Waicukauski, J. Colburn, M. Sonawane



## Table of Contents

### SESSION 7 TACKLING TIMING AND POWER DURING TEST

Session Chair: M. Hashimoto

- 7.1 *Mitigating Voltage Droop During Scan with Variable Shift Frequency* **78**  
J. Schulze, R. Tally
- 7.2 *At-speed Capture Power Reduction Using Layout-aware Granular Clock Gate Enable Controls* **86**  
R. Shaik, P. Wilson, K. Agarwal, H. Sanjay, R. Tiwari, K. Lath, S. Ravi
- 7.3 *Fast BIST of I/O Pin AC Specifications and Inter-Chip Delays* **96**  
S. Sunter, S. Shaikh, Q. Lin

### SESSION 8 LEARN FROM THE EXPERTS: HIGH VOLUME MANUFACTURING

Session Chair: P. Nigh

- 8.1 *Latent Defect Detection in Microcontroller Embedded Flash Test Using Device Stress and Wordline Outlier Screening* **104**  
A. Kux, R. Ullmann, T. Kern, R. Strunz, H. Melzner, S. Beuven, A. Haase
- 8.2 *Statistical Silicon Results of Dynamic Power Integrity Control of ATE for Eliminating Overkills and Underkills* **111**  
M. Ishida, T. Kusaka, T. Nakura, S. Komatsu, K. Asada
- 8.3 *INVITED PAPER: Challenges of Testing 100M chips* **121**  
S. Pagarkar

### SESSION 9 RF TEST: DIGITAL ATE, RADIOS, RADARS

Session Chair: S. Shaikh

- 9.1 *Low-Cost Phase Noise Testing of Complex RF ICs Using Standard Digital ATE* **122**  
S. David-Grignot, F. Azais, L. Latorre, F. Lefevre
- 9.2 *INVITED PAPER: Market Opportunities and Testing Challenges for Millimeter-Wave Radios and Radars* **131**  
B. Floyd
- 9.3 *A Novel RF Self-Test for a Combo SoC on Digital ATE with Multi-Site Applications* **132**  
C-H. Peng, C-Y. Yang, A. Tsu, C-J. Tsai, Y. Chen, C-Y. Lin, K. Hong, K. Kao, P. Liang, C-L. Tsai, C. Chien, H-C. Hwang

### SESSION 10 "FOOL" NYQUIST, FIX NONLINEARITY, TOLERATE JITTER

Session Chair: K. Butler

- 10.1 *Low-Distortion Signal Generation for ADC Testing* **140**  
F. Abe, Y. Kobayashi, K. Sawada, K. Kato, O. Kobayashi, H. Kobayashi
- 10.2 *A Built-in Self-Test Circuit for Jitter Tolerance Measurement in High-Speed Wireline Receivers* **150**  
M-J. Park, J. Kim
- 10.3 *INVITED PAPER: Teaching an Old Dog New Tricks: Views on the Future of Mixed-Signal IC Design* **156**  
B. Murmann

## Table of Contents

### SESSION 11 EMBEDDED SYSTEMS: FROM FIRMWARE TO LARGE-SCALE APPLICATIONS

Session Chair: C. Liu

- 11.1 *INVITED PAPER: Top Ten Challenges in Big Data Security and Privacy* **157**  
P. Murthy
- 11.2 *INVITED PAPER: Software in a Hardware View: New Models for HW-dependent Software in SoC Verification and Test* **158**  
C. Villarraga, B. Schmidt, B. Bao, R. Raman, C. Bartsch, T. Fehmel,  
D. Stoffel, W. Kunz
- 11.3 *INVITED PAPER: Compositional Verification Using Formal Analysis for a Flight Critical System* **167**  
G. Brat

### SESSION 12 TEST ENABLES TECHNOLOGY BRINGUP

Session Chair: E. Amyeen

- 12.1 *INVITED PAPER: Design, Technology and Yield in the Post-Moore Era* **168**  
G. Yeric
- 12.2 *INVITED PAPER: The Importance of DFX, A Foundry Perspective* **169**  
S. Adham, J. Chang, H. Liao, J. Hung, T-H. Hsieh
- 12.3 *INVITED PAPER: Yield and Performance Improvement Through Technology-Design Co-optimization in Advanced Technology Nodes* **175**  
Y. Liang

### SESSION 13\* CHALLENGES IN TESTING MEMS DEVICES

Moderator and Organizer: R. Chrusciel

- 13.1 *INVITED PAPER: MEMS Testing Challenges* **N/A**  
R. Chrusciel
- 13.2 *INVITED PAPER: MEMS Handling and Test Requirements* **N/A**  
R. Chrusciel, A. Mancosu, R. O'Reilly, H. Nozawa, M. Dewey
- 13.3 *INVITED PAPER: Solutions for MEMS Testing* **N/A**  
R. Chrusciel, A. Mancosu, R. O'Reilly, H. Nozawa, M. Dewey

### SESSION 14 ADVANCES IN PACKAGING AND PROBING

Session Chair: S. Ghosh

- 14.1 *INVITED PAPER: Managing Signal, Power and Thermal Integrity for 3D Integration* **176**  
M. Swaminathan
- 14.2 *Direct Probing on Large-Array Fine-Pitch Micro-Bumps of a Wide-I/O Logic-Memory Interface* **177**  
EJ. Marinissen, B. De Wachter, K. Smith, J. Kiesewetter, M. Taouil,  
S. Hamdioui
- 14.3 *Wafer-level Chip-scale Package Copper Pillar Probing* **187**  
H. Chen, H-C. Lin, C-N. Peng, M-J. Wang

\*Presented at ITC, but not included in proceedings

## Table of Contents

### SESSION 15 BUILDING ROBUST SYSTEMS: UNDER TEST AND IN THE WILD

Session Chair: H. Konuk

- 15.1 *INVITED PAPER: A Tale of Two Lives: Under Test and in the Wild* **193**  
B. Schroeder
- 15.2 *Soft Error Resiliency Characterization and Improvement on IBM BlueGene/Q Processor Using Accelerated Proton Irradiation* **194**  
C-Y. Cher, P. Muller, R. Haring, D. Satterfield, T. Musta, T. Gooding,  
K. Davis, M. Dombrowa, G. Kopcsay, R. Senger, Y. Sugawara,  
K. Sugavanam
- 15.3 *Efficient RAS Support for Die-stacked DRAM* **200**  
H. Jeon, G. Loh, M. Annavaram

### SESSION 16 EMERGING SOS CHALLENGES

Session Chair: N. Touba

- 16.1 *Systematic Approach for Trim Test-Time Optimization: Case Study on a Multicore RF SOC* **210**  
R. Mittal, M. Kawoosa, R. Parekhji
- 16.2 *INVITED PAPER: Thermal-Aware Mobile SoC Design and Test in 14nm Finfet Technology* **219**  
B-H. Lee
- 16.3 *Robustness of TAP-based Scan Networks* **220**  
F. Ghani Zadegan, G. Carlsson, E. Larsson

### SESSION 17 CODING, COVERAGE, VMIN, AND REPAIR: TRADEOFFS IN TODAY'S EMBEDDED MEMORIES

Session Chair: S. Hamdioui

- 17.1 *INVITED PAPER: Trading-Off On-Die Observability for Cache Minimum Supply Voltage Reduction in System-on-Chip (SoC) Processors* **230**  
K. Bowman
- 17.2 *INVITED PAPER: Design, Test & Repair Methodology for FinFET-based Memories* **231**  
Y. Zorian
- 17.3 *A Tag-based Solution for Efficient Utilization of Efuse for Memory Repair* **232**  
K. Shah, H. Ellur

### SESSION 18 BIG DATA: BIG PROBLEM OR OPPORTUNITY FOR TEST?

Session Chair: P. Maxwell

- 18.1 *Spatiotemporal Wafer-level Correlation Modeling with Progressive Sampling: A Pathway to HVM Yield Estimation* **239**  
A. Ahmadi, K. Huang, S. Natarajan, J. Carulli Jr., Y. Makris
- 18.2 *Yield Optimization Using Advanced Statistical Correlation Methods* **249**  
J. Tikkenan, S. Siatkowski, N. Sumikawa, L-C. Wang, M. Abadir
- 18.3 *INVITED PAPER: Big Data and Test* **259**  
A. Gattiker

## Table of Contents

### SESSION 19 STATISTICAL APPROACHES TO AMS DESIGN AND TEST

Session Chair: R. Clancy

- 19.1 *Bayesian Model Fusion: Enabling Test Cost Reduction of Analog/RF Circuits via Wafer-level Spatial Variation Modeling* **260**  
S. Zhang, X. Li, R. Blanton, J. Silva, J. Carulli, K. Butler
- 19.2 *IC Laser Trimming Speed-Up through Wafer-level Spatial Correlation Modeling* **270**  
C. Xanthopoulos, K. Huang, A. Poonawala, A. Nahar, B. Orr, J. Carulli Jr., Y. Makris
- 19.3 *INVITED PAPER: Design and Test of Analog Circuits Toward Sub-PPM Level* **277**  
G. Gielen, W. Dobbelaere, R. Vanhooren, A. Coyette, B. Esen

### SESSION 20 TEST AND YIELD GO 3-D

Session Chair: L. Winemberg

- 20.1 *Redundancy Architectures for Channel-based 3D DRAM Yield Improvement* **279**  
B-Y. Lin, W-T. Chiang, C-W. Wu, M. Lee, H-C. Lin, C-N. Peng, M-J. Wang
- 20.2 *Vesuvius-3D: A 3D-DFT Demonstrator* **286**  
E.J. Marinissen, B. De Wachter, S. O'Loughlin, S. Deutsch, C. Papamietis, T. Burgherr
- 20.3 *A Distributed, Reconfigurable, and Reusable BIST Infrastructure for 3D-Stacked ICs* **296**  
M. Agrawal, K. Chakrabarty, B. Eklow

### SESSION 21 BOARDS AND TEST: NOT YOUR DAD'S BOARD TEST

Session Chair: Z. Conroy

- 21.1 *INVITED PAPER: Interposer Test - Testing PCBs That Have Shrunk 100X* **306**  
T.M. Mak
- 21.2 *Knowledge Discovery and Knowledge Transfer in Board-level Functional Fault Diagnosis* **307**  
F. Ye, Z. Zhang, K. Chakrabarty, X. Gu
- 21.3 *Board Manufacturing Test Correlation to IC Manufacturing Test* **317**  
C. Shirley, W. Daasch, P. Nigh, Z. Conroy

### SESSION 22 VALIDATION: PRE-SILICON, EMULATION, POST-SILICON

Session Chair: T. Chakraborty

- 22.1 *On-Chip Constrained Random Stimuli Generation for Post-Silicon Validation Using Compact Masks* **325**  
X. Shi, N. Nicolici
- 22.2 *INVITED PAPER: Emulation and its Connection to Test* **335**  
K. Larsen
- 22.3 *Clustering-based Failure Triage for RTL Regression Debugging* **336**  
Z. Poulos, A. Veneris



## Table of Contents

### SESSION 23 RAM TEST AND REPAIR: TODAY AND TOMORROW

Session Chair; M. D'Abreu

- 23.1 *A Reusable BIST with Software-assisted Auto Repair Technology for Improved Memory and IO Debug, Validation and Test Time* **346**  
B. Querbach, R. Khanna, D. Blankenbeckler, Y. Zhang, R. Anderson,  
D. Ellis, Z. Schoenborn, S. Deyati, P. Chiang
- 23.2 *Analytical MRAM Test* **356**  
R. Robertazzi, J. Nowak, J. Sun
- 23.3 *Read-disturb Fault Detection in STT-MRAM* **366**  
R. Bishnoi, M. Ebrahimi, F. Oboril, M. Tahoori

### SESSION 24 CONNECTING PROCESS VARIATION, YIELD, AND DIAGNOSIS

Session Chair: S. Goel

- 24.1 *Intra-Die Process Variation-aware Anomaly Detection in FPGAs* **373**  
Y. Pino, V. Jyothi, M. French
- 24.2 *Feature Engineering with Canonical Analysis for Effective Statistical Tests Screening Test Escapes* **379**  
F. Lin, C-K. Hsu, K-T. Cheng
- 24.3 *Logic Characterization Vehicle Design for Maximal Information Extraction for Yield Learning* **389**  
S. Blanton, B. Niwenhuis, C. Taylor

### SESSION 25 FUNCTIONAL TESTING: A FRESH LOOK

Session Chair: C. Pyron

- 25.1 *INVITED PAPER: The Case for Analyzing System-level Failures Using Structural Patterns* **399**  
H. Chen
- 25.2 *EAGLE: A Regression Model for Fault Coverage Estimation Using a Simulation-based Metric* **400**  
S. Mirkhani, J. Abraham
- 25.3 *Comparing the Effectiveness of Cache-resident Tests Against Cycle-accurate Deterministic Functional Patterns* **410**  
S. Gurumurthy, M. Pratapgarhwala, C. Gilgan, J. Rearick

### SESSION 26 THINK YOU KNOW ATPG? THINK AGAIN

Session Chair: S. Hellebrand

- 26.1 *Fault Sharing in a Copy-on-Write-based ATPG System* **418**  
X. Cai, P. Wohl, D. Martin
- 26.2 *Test Pattern Generation in Presence of Unknown Values Based on Restricted Symbolic Logic* **426**  
D. Erb, K. Scheibler, M. Kochte, M. Sauer, H-J. Wunderlich, B. Becker
- 26.3 *Efficient SAT-based ATPG Techniques for All Multiple Stuck-At Faults* **436**  
M. Fujita, A. Mishchenko



## Table of Contents

### SESSION 27 STAY "TUNED" FOR ANALOG TESTING

Session Chair: A. Meixner

- 27.1 *Testing Silicon TV Tuners on ATE Without TV Signal Generator* **446**  
Y. Fan, A. Verma, J. Janney, S. Kumar
- 27.2 *A Self-Tuning Structure for Buck Converters Based on Alternative Test* **455**  
X. Wang, K. Blanchard, S. Estella, A. Chatterjee
- 27.3 *Fast Co-test of Linearity and Spectral Performance with Noncoherent  
Sampled and Amplitude-Clipped Data* **465**  
L. Xu, D. Chen

### SESSION 28 ATTACKS AND COUNTERMEASURES FOR SECURE CHIPS

Session Chair: K. Huang

- 28.1 *Board Security Enhancement Using New Locking SIB-based  
Architectures* **473**  
J. Dworak, Z. Conroy, A. Crouch, J. Potter
- 28.2 *Counterfeit IC Detection Using Light Emission* **483**  
P. Song, F. Stellari, A. Weger
- 28.3 *Test-Mode-only Scan Attack and Countermeasure for  
Contemporary Scan Architectures* **491**  
S. Saeed, S. Ali, O. Sinanoglu, R. Karri

### SESSION 29 LOGIC TEST COMPRESSION + LOGIC BIST

Session Chair: M. Vachon

- 29.1 *Improving Test Compression with Scan Feedforward Techniques* **499**  
S. Muthyala, N. Touba
- 29.2 *A Diagnosis-friendly LBIST Architecture with Property Checking* **509**  
S. Prabhu, V. Acharya, S. Bagri, M. Hsiao
- 29.3 *FAST-BIST: Faster-than-At-Speed BIST Targeting Hidden Delay Defects* **518**  
S. Hellebrand, T. Indlekofer, M. Kampmann, M. Kochte, C. Liu,  
H-J. Wunderlich

### SESSION 30 WHAT'S WRONG WITH MY CHIP?

Session Chair: E. Rentschler

- 30.1 *An Efficient Diagnosis-aware Pattern Generation Procedure for Transition  
Faults* **526**  
K-J. Lee C-H. Wu
- 30.2 *Divide and Conquer Diagnosis for Multiple Defects* **536**  
S-M. Chao, P-J. Chen, J-Y. Chen, P-H. Chen, A-F. Lin, C-M. Li, P-Y. Hsueh,  
C-Y. Kuo, Y-Y. Chen, J-N. Li
- 30.3 *Massive Signal Tracing Using On-Chip DRAM for In-System Silicon Debug* **544**  
S. Deutsch, K. Chakrabarty

## Table of Contents

### IEEE TTTC E. J. MCCLUSKEY DOCTORAL DISSERTATION COMPETITION: FINAL ROUND

Session Chair: M. Portolan

DDC 1 *Error Prediction and Detection Methodologies for Reliable Circuit  
Operation Under NBTI* **554**  
J. Vazquez-Hernandez

DDC 2 *DFST: Design for Secure Testability* **564**  
S. Saeed

DDC 3 *Analysis and Test of the Effects of Single Event Upsets Affecting the  
Configuration Memory of SRAM-based FPGAs* **574**  
L. Cassano

#### Additional Papers

*A Test Probe for TSV Using Resonant Inductive Coupling* **584**  
R. Rashidzadeh, I. Basith

*Optimizing Redundancy Design for Chip-Multiprocessors for Flexible Utility Functions* **594**  
D. Cheng, S. Gupta

#### PANEL 1\* ANALOG DESIGN-FOR-TEST: WHAT'S THE REAL STORY?

Moderator: R. Aitken, Organizer: M. Soma

Panelists: T. Fiez, S. Kumar, J. Paramesh, S. Sunter

#### PANEL 2\* OPEN PROBLEMS IN DESIGN, VERIFICATION AND TEST: WHY IS IT (NOT) BUSINESS AS USUAL?

Moderator: T. Cheng, Organizer: R. Parekhji

Panelists: S. Agarwala, P. Cunningham, S. Pateras, R. Puri,  
R. Senthinathan, S. Venkataraman

#### ELEVATOR TALKS\*

Session Chairs: M. Maniatakos, Y. Li

Presenters: S. Bhattacharyya, K. Chakrabarty, A. Chatterjee,  
J. Dworak, S. Eichenberger, X. Li, D. Mukhopadaya, N. Nicolici,  
D. O'Brien, D. Park, B. Petrakis, T-C. Yang

#### ITC 2013 BEST PAPER\*

*Test Time Reduction with SATOM: Simultaneous AC-DC Test with Orthogonal  
Multi-excitations*

D. Chen, Z. Yu, K. Maniar, M. Nowrozi

\*Presented at ITC, but not included in proceedings.



## Table of Contents

### POSTER SESSION\*

Session Chair: W. Eklow

- PO 1 *Two-Step Dynamic Encoding for Linear Decompressors*  
E. Gizdarski
- PO 2 *Handling Xs in Test Simulation—A Case Study*  
K-H Chang, Y-T Liu, C. Browy
- PO 3 *Multi-bit Delta-Sigma TDC BOST for Timing Test*  
H. Kobayashi, T. Chujo, D. Hirabayashi, M. Tsuji, K. Sato
- PO 4 *Detection and Diagnostics of Anomalous Thermal Behavior in 28-nm High-Power SoC Devices*  
S. Dasnurkar, N. Joshi, A. Devatha, K. Dusey, P. Bhadri
- PO 5 *System-level Test and Fault Isolation*  
J. Block, T. Anayama
- PO 6 *Leveraging Design Pipelines in DFT*  
R. Rajanaray
- PO 7 *An Adaptive TMR Flip-Flop Architecture for Fault-Tolerance-Power Optimization*  
L. Cassano, G. Di Natale, A. Bosio
- PO 8 *Considerations for Assimilating Competing Standards*  
B. Atwell, A. Bair, C. Barnhart, B. Bruce, J. Johnson, SiliconAid Solutions
- PO 9 *Minimization of Yield Loss in Wafer Test by Separated I/O Channels in Probe Card with ASIC Analog Switches*  
S. Joo, J. Kim, S. Yoo, J. Joo
- PO 10 *PaRent (Parallel and Concurrent) Testing for Complex Mixed-Signal Devices*  
Q. Khasawneh, P. Gui, J. Dworak, Q. Zhao
- PO 11 *At-Speed Testing of Inter-Clock Domain Paths*  
S. Bahl, S. Khullar, S. Rungta
- PO 12 *A Fault Injection Methodology for Single-Event Upsets Emulation of Xilinx SRAM-based FPGAs*  
D. Rolfo, S. Di Carlo, P. Prinetto, P. Trotta
- PO 13 *Core Self-Test Execution Management*  
P. Bernardi, R. Cantoro, E. Sanchez, O. Ballan, S. De Luca, R. Meregalli, A. Sansonetti
- PO 14 *Improving ATPG Effectiveness Using Random Resistive Fault Analysis at RTL*  
S. Shaikh
- PO 15 *Detection and Screening of Small Delay Defects Impacting System Functionality in 28-nm/20-nm SoC*  
S. Dasnurkar, A. Devatha, P. Bhadri
- PO 16 *Real-Time Supply Voltage Sensor for Trace-based Fault Localization*  
M. Hashimoto, M. Ueno, T. Onoye
- PO 17 *Group-Delay Testing for Envelope Tracking in a Radio Frequency Integrated Circuit*  
R. Rafique
- PO 18 *Shadow Bin: A Test Executor on Steroids*  
V. Shirgur, C. Mamuad, J. Sarmiento, G. Ponnuvel
- PO 19 *Rnv8T NVSRAM Test Time Reduction by Combining RRAM Forming and RRAM Defect Detection Prior to Functional Tests*  
B-C. Bai, C-M. Li, C-A Chen, Y-W. Chen, M-H. Wu, P-Y. Chen, K-L. Luo, C-L. Hsu, L-C. Cheng, C-M. Li
- PO 20 *Pattern Generation for Understanding Timing Sensitivity to Power Supply Noise*  
T. Zhang, Y. Gao, D. Walker
- PO 21 *A Production ATE Solution for Microwave and Millimeter Automotive Radar*  
D. Morris
- PO 22 *Physical Design for Debug – A Low-Cost Method to Extend DFT*  
J. Giacobbe

\*Presented at ITC, but not included in proceedings



## Table of Contents

### POSTER SESSION\*

- PO 23 *A Novel Scan-based Diagnostics Approach to Enable Rapid Yield Learning for Production Ramp*  
D. Wee, J. Murthy, A. Aggarwal, M. Rathinasabapathy, N. Seow, S. Shaikh, G. Eves
- PO 24 *Copula-based Techniques to Identify Miscorrelating Outlier Between Efficient Test and Use*  
Y-S. Wang, W. Daasch
- PO 25 *Emerging Test Standards*  
IEEE Standards Working Group Representatives
- PO 26 *Enhanced OCC and Ideal Logic BIST*  
R. Rajanaray
- PO 27 *Multi-Tier Power-aware Verification of SoC ICs*  
D. Akselrod, S. Golubkov, P. Liu
- PO 28 *Intro to RITdb – Comprehensive Standards to Support Monitoring, Analysis and Adaptive Test*  
S. Ajouri
- PO 29 *Mixed-Signal Tester-on-Chip (ToC)*  
H. Ehrenberg\* T. Wenzel, J. Heiber
- PO 30 *System-level Test of Complex SoC's Using Protocol-aware ATE*  
S. Molavi
- PO 31 *IEEE 1687 (iJTAG) – Enabling In-System Test Automation*  
Y. Lee, W. Wang, H-M. Li
- PO 32 *Rapidly Sourcing Yield Excursions with Scan Analysis*  
E. McArthur, B. Keller
- PO 33 *Challenges and Chances in Network Reliability*  
Z. Zhang, X. Gu, Z. Wang, X. Fan, G. Chen, T. Xu, X Liu
- PO 34 *System State Retention Verification Using ATPG for Debug*  
P. Venkitaraman, J. Abraham
- PO 35 *An Integrated Enterprise-wide Yield Monitoring and Root Cause Analysis System*  
D. Wee, J-Y. Siow, J. Chan, M. Mattingly, G. Eves
- PO 36 *Reducing the Effort for Board-level Functional Diagnosis Through Incremental Test Execution*  
L. Cassano, C. Bolchini
- PO 37 *An Extensible Low-Density Parity-Check Decoder for Solid-State Drive*  
T. Kang, H. Yi
- PO 38 *Fault Diagnosis Techniques for Defect Inside Library Cells*  
R. Guo, C. Schuemyer, E. Gizdarski, Y. Kanzawa
- PO 39 *Using Boolean Tests to Improve Detection of Transistor Stuck-Open Faults in CMOS Digital Logic Circuits*  
S. Reddy, X. Lin, J. Rajski
- PO 40 *WLCSP Massive Parallel Test Solution*  
A. Monga, H. Takuya
- PO 41 *Advanced Parametric Probe Challenges*  
S. Kuhnert, R. Lakshmanan
- PO 42 *The Evolution of Waveform Generation, Measurement and Analysis, and Its Impact on Test*  
S. Tilden
- PO 43 *Challenges in Testing MEMS Inertial Devices*  
R. Chrusciel

\*Presented at ITC, but not included in proceedings